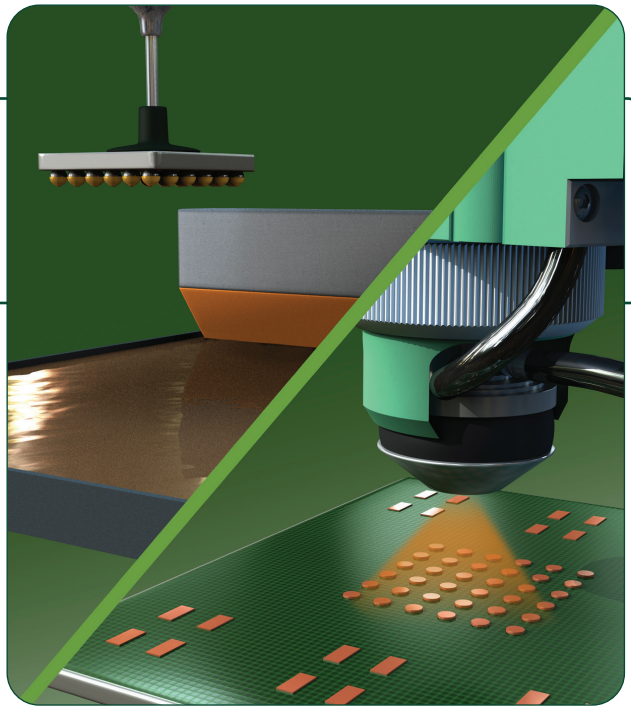
PRODUCT DATA SHEET

NC-26-A

Flip-Chip Flux



Introduction

Flip-Chip Flux NC-26-A is a halogen-free, no-clean flip-chip dipping flux which is designed to leave a completely benign, clear residue. The reduction in residue optimizes underfill adhesion and decreases possible outgassing during underfill cure.

Features

- Designed for flip-chip dipping applications
- Tackiness suitable for holding die during assembly
- Bubble-free airless packaging
- Ultra-low residue
- Halogen-free
- No-clean

Properties

	Value	Test Method
Flux Type Classification	REL0	J-STD-004 (IPC-TM-650: 2.3.32 and 2.3.33)
Color	Light tan	Visual
Typical Viscosity	4kcps	Brookfield DV-1.51CPE Spindle @ 10rpm after 5 minutes
Typical Tack Strength	200g/cm^2	J-STD-005 (IPC-TM-650: 2.4.44)
Typical Acid Value	36mg KOH/g	Titration
SIR (Ohms)	Pass	J-STD-004 (IPC-TM-650: 2.6.3.3 IPC-B-24)
Typical Post Reflow Residual Weight	~5%	TGA Data
Working Life	≥8 hours	Customer experience (dipping)
Shelf Life	6 months when stored at 0 to 30°C	Viscosity change/ microscope examination

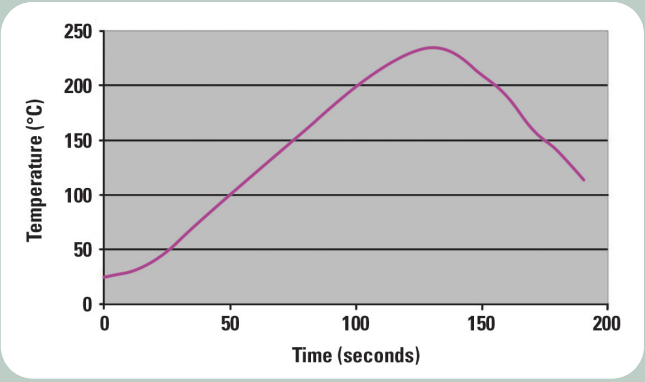
All information is for reference only.
Not to be used as incoming product specifications.

Application

Flip-Chip Flux NC-26-A will have strong adhesion to epoxy-based underfill materials, especially epoxy-amine and epoxy-acid based chemistries. **Flip-Chip Flux NC-26-A** should also be suitable for use with many epoxy-anhydride systems.

Reflow

Recommended Profile:



Flip-Chip Flux NC-26-A is intended to be used in a nitrogen reflow environment of 100ppm oxygen or less. Some applications can utilize this material in an air environment, although best results will be obtained in an inert atmosphere. **Flip-Chip Flux NC-26-A** can be used on many surface finishes including immersion Ag, Cu, and AuNi. These surfaces can be soldered with SnPb or Pb-free alloys, but require nitrogen if reflow temperatures exceed 240°C.

From One Engineer To Another®

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Cleaning

Flip-Chip Flux NC-26-A is designed for no-clean applications. If necessary, the flux can be removed by using a commercially available flux cleaner. Please contact an Indium Corporation Technical Service Engineer for recommendations of cleaners to suit your process needs.

Packaging

Flip-Chip Flux NC-26-A is most commonly available in 10–30g syringes. Other packaging can be provided to meet specific requirements.

Storage

Flip-Chip Flux NC-26-A syringes and cartridges should be stored tip down for maximum shelf life. **Flip-Chip Flux NC-26-A** should be allowed to reach ambient temperature before use if stored cold.

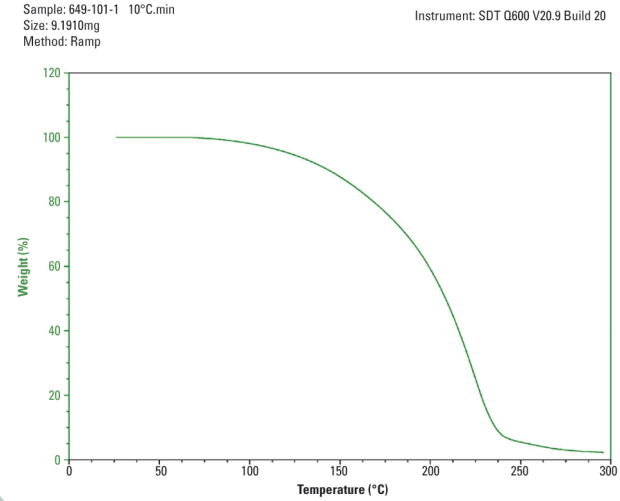
Technical Support

Indium Corporation sets the industry standard in providing rapid response, onsite technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

Please refer to the SDS document within the product shipment, or contact our local team to receive a copy.

Thermogravimetric Analysis (TGA)



TGA was performed at a ramp rate of 10°C per minute.

All of Indium Corporation's solder paste and preform manufacturing facilities are IATF 16949:2016 certified.
Indium Corporation is an ISO 9001:2015 registered company.

Contact our engineers: **askus@indium.com**
Learn more: **www.indium.com**

ASIA +65 6268 8678 • CHINA +86 (0) 512 628 34900 • EUROPE +44 (0) 1908 580400 • USA +1 315 853 4900